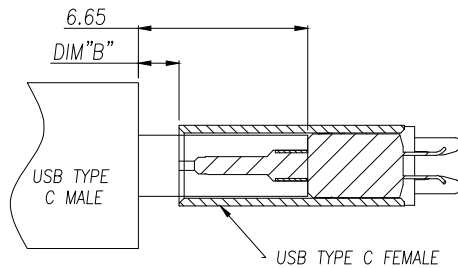
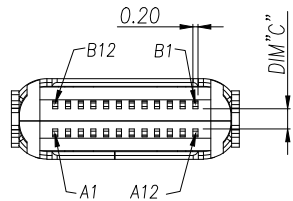


REV.	DESCRIPTION	ECN NO.	NAME	DATE

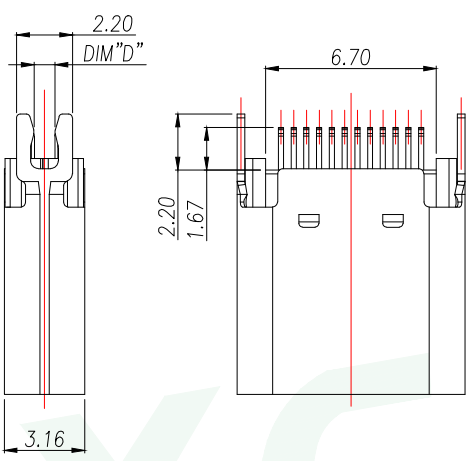
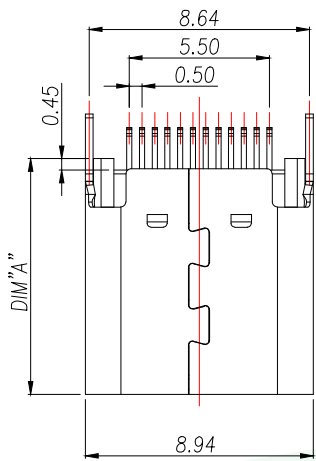
1



AFTER ASSEMBLY

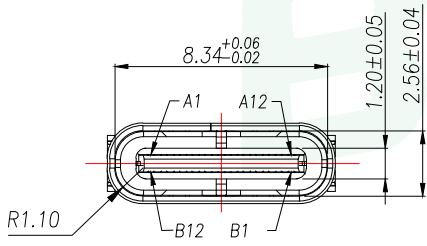
NOTE:  
 1.MATERIAL SPECIFICATION:  
 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.  
 2.CONTACTS: COPPER ALLOY(C1814)  
 3.MID PLATE: STAINLESS STEEL(SUS301)  
 4.FRONT SHELL: STAINLESS STEEL(SUS304)  
 5.EMI PLATE: STAINLESS STEEL(SUS304)  
 2.PLATING SPECIFICATION:  
 2-1.TERMINAL:  
 Ni 50u" MIN. UNDER PLATED OVER ALL.  
 Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.  
 CONTACT FUNCTIONAL AREA PLATED : Au 3u"  
 CONTACT SOLDER AREA PLATED : Au G/F"  
 2-2.FRONT SHELL:  
 Ni 30u" MIN. UNDER PLATED OVER ALL.  
 2-3.MID PLATE&EMI PLATE:  
 CLEAR ONLY  
 3.MECHANICAL PERFORMANCE,  
 3-1.INSERTION FORCE: 0.5~2.0kgf.  
 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.  
 3-3.DURABILITY: 10000 CYCLES.  
 4.ELECTRICAL PERFORMANCE,  
 4-1. CURRENT RATING:5.0A  
 VOLTAGE RATING:5.0V  
 4-2. LLCR:  
 VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.  
 SHIELD: 50mΩ/MAX.  
 LLCR MAX. CHANGE OF ALL PINS: 10mΩ.  
 4-3.INSULATION RESISTANCE: 100MΩ MIN  
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.  
 5. ENVIRONMENTAL PERFORMANCE:  
 OPERATING TEMPERATURE: -40°C~+85°C.  
 6.IR REFLOW:  
 THE PEAK TEMPERATURE ON THE BOARD SHALL  
 BE MAINTAINED FOR 10 SECONDS AT 260°C.

2



3

4

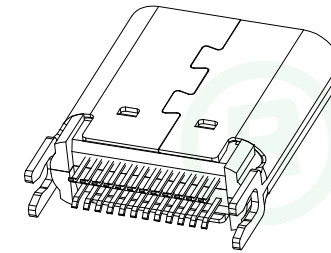
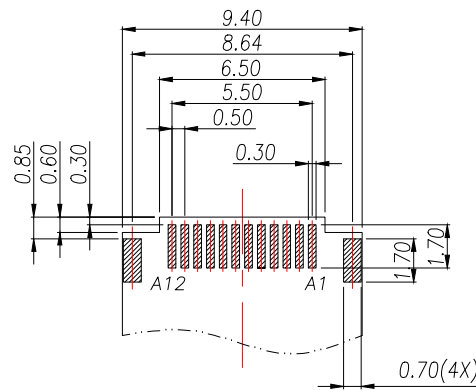
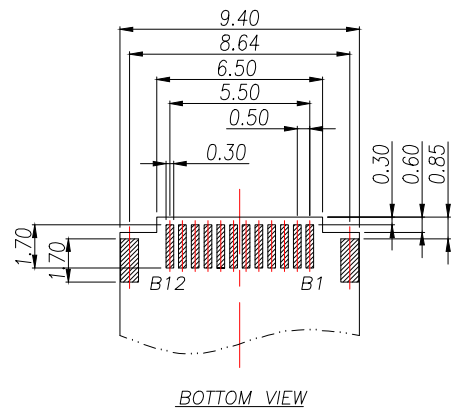


A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TXp1	TXn1	Vbus	CC1	D+	D-	SBU1	Vbus	RXn2	RXp2	GND
GND	RXp1	RXn1	Vbus	SBU2	D-	D+	CC2	Vbus	TXn2	TXp2	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

5

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				
DIM. TOL.		TITLE: USB C F SPLINT CONN. WITH EMI PCB=0.8&1.0				
X		DWG. NO.: UC13-OB24F00P11		DRAWN: MAX		
X.X	±0.30	PART NO.: UC13-OB24F00P11		CHECKED: ELLA		
X.XX	±0.25	UNIT: mm		APPROVED: WILL		
X.XXX	±0.15	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	
GENERAL ANGLE:	±3°					

REV.	DESCRIPTION	ECN NO.	NAME	DATE



THICKNESS SEE TABLE1;DEFAULT TOLERANCE:±0.05

TABLE 1

P/N	DIM A	DIM B	DIM C	DIM D	THICKNESS OF THE PCB	QTY/TUBE	QTY/BOX
TYPEC-1103-BRP24	10.40	0.45	0.80	0.82	0.80±0.05MM	50	18000

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				
DIM. TOL.		TITLE: USB C F SPLINT CONN. WITH EMI PCB=0.8&1.0				
X		DWG. NO.: UC13-OB24F00P11		DRAWN: MAX		
X.X	±0.30	PART NO.: UC13-OB24F00P11		CHECKED: ELLA		
X.XX	±0.25	UNIT: mm		APPROVED: WILL		
X.XXX	±0.15	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	
GENERAL ANGLE:	±3°					

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